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Taniguchi et al.

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(54) **ADHESIVE TAPE FOR SEMICONDUCTOR MANUFACTURING**

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(*) Notice: This patent is subject to a terminal disclaimer.

(**) Term: **14 Years**

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(30) **Foreign Application Priority Data**

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(51) **LOC (9) Cl.** **13-03**
(52) **U.S. Cl.** **D13/182**
(58) **Field of Classification Search** .... D13/182; 156/235, 248; 428/343, 345, 353, 355 R; 438/114, 455, 460, 463
See application file for complete search history.

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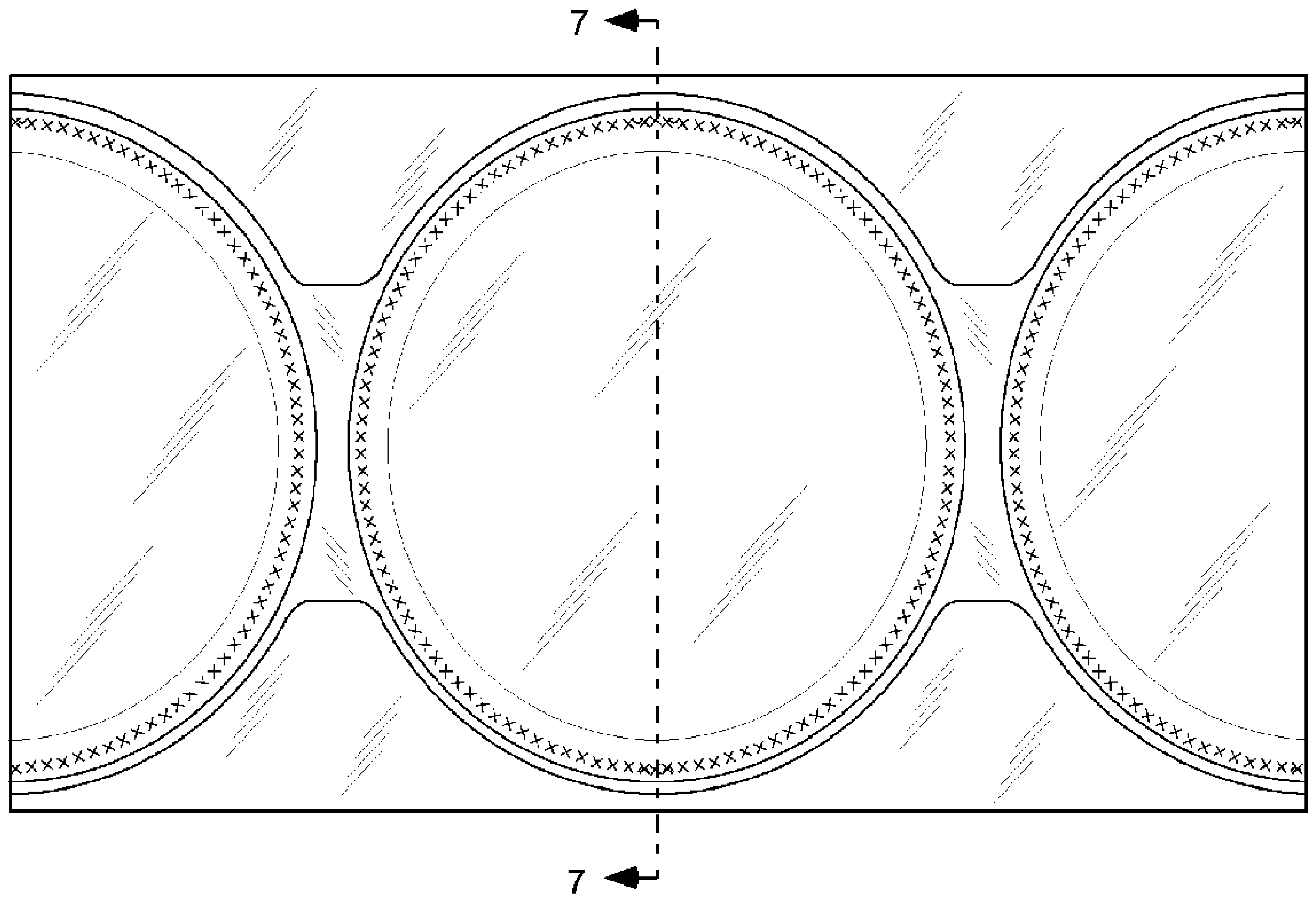
(57) **CLAIM**

The ornamental design for an adhesive tape for semiconductor manufacturing, as shown and described.

DESCRIPTION

FIG. **1** is a top plan view of our new design;
FIG. **2** is a bottom plan view;
FIG. **3** is a left side view;
FIG. **4** is a right side view;
FIG. **5** is a rear side view;
FIG. **6** is a front side view;
FIG. **7** is a cross sectional view taken at line **7**-**7** of FIG. **1**;
FIG. **8** is an exploded view; and,
FIG. **9** is an enlarged view of the lower and left portion of the claimed design shown in FIG. **1** for completeness of illustration.

1 Claim, 4 Drawing Sheets



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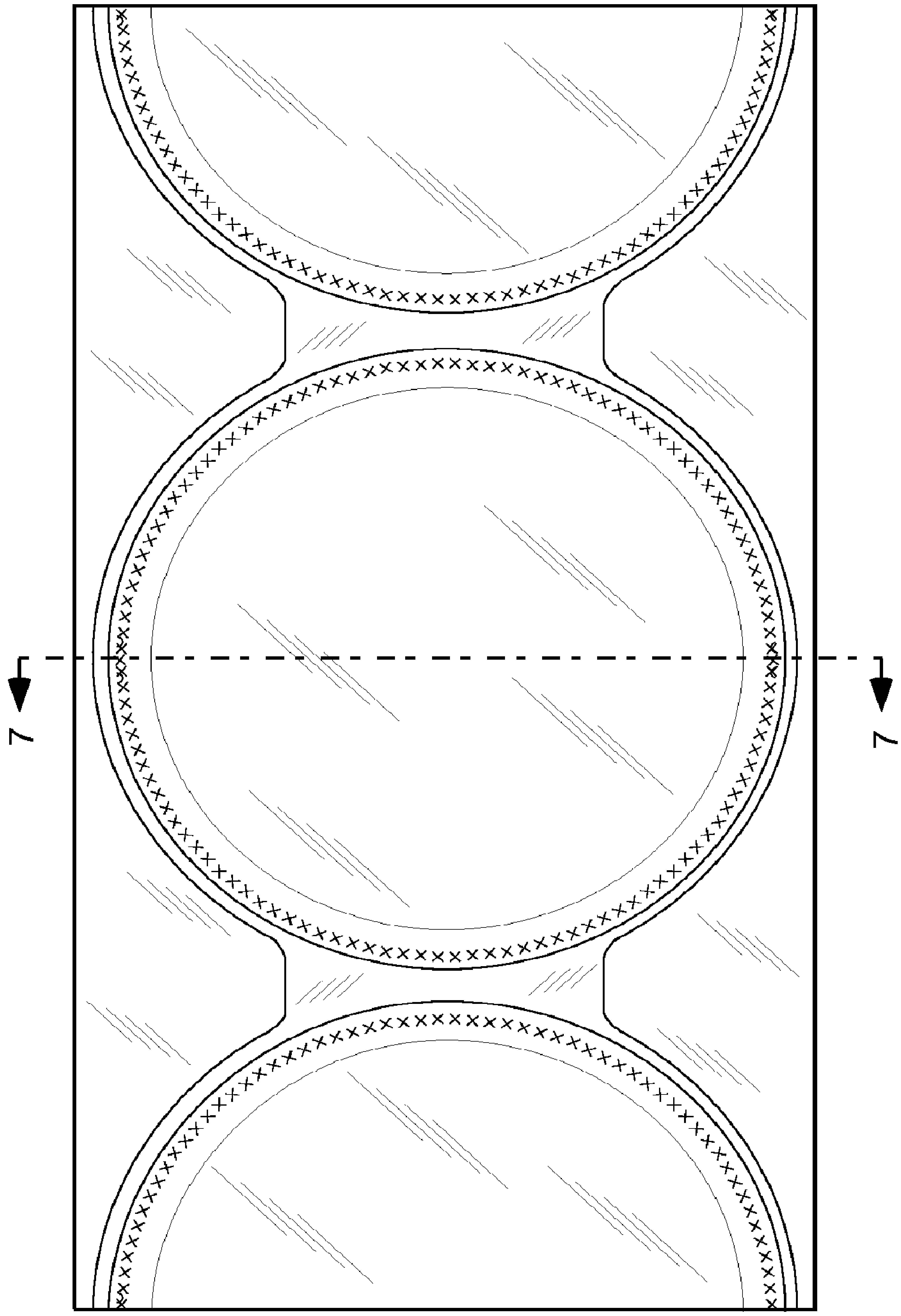

Fig. 1

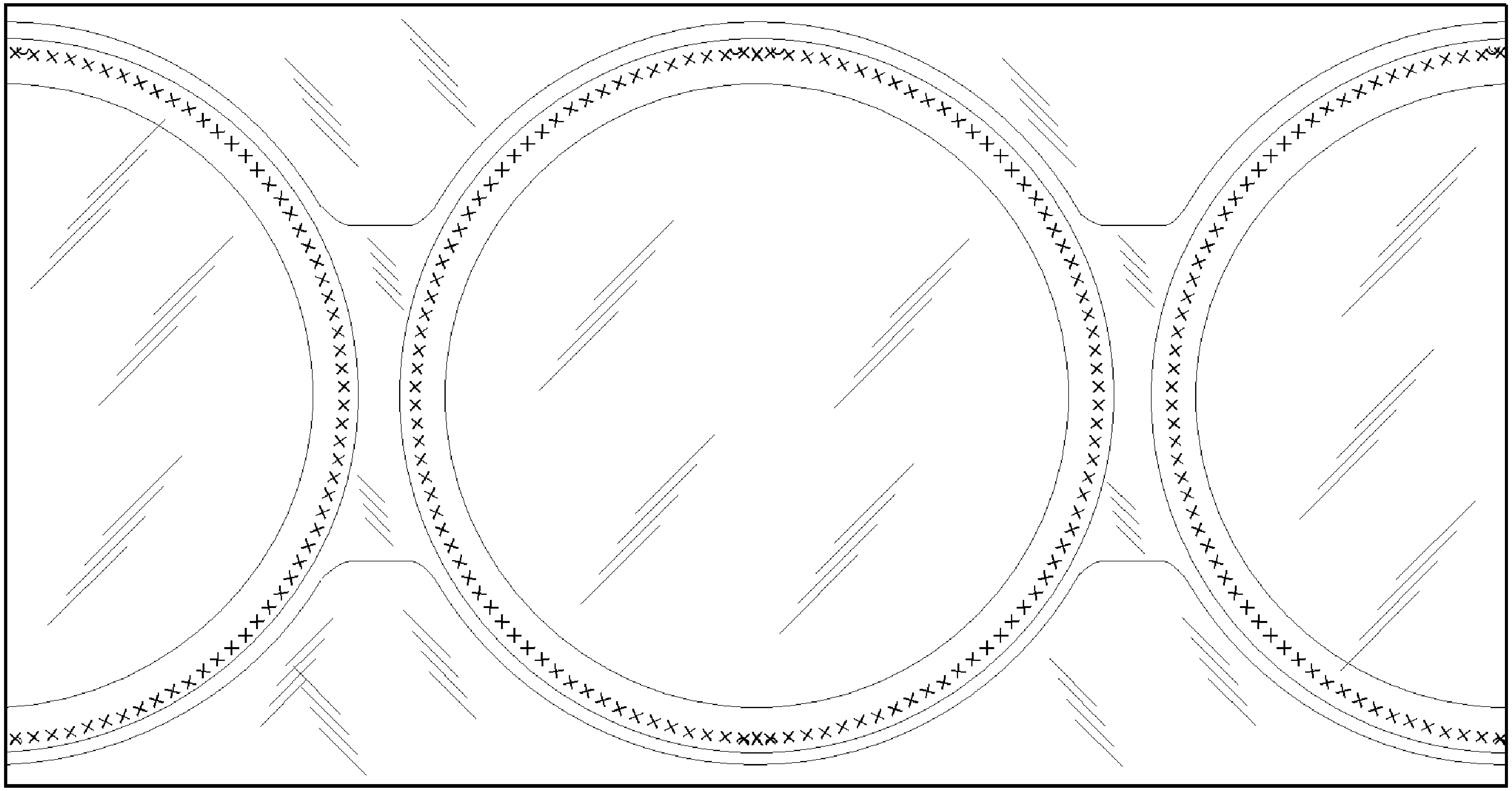

Fig. 2

Fig. 3

Fig. 4

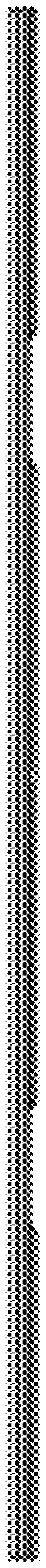

Fig. 5

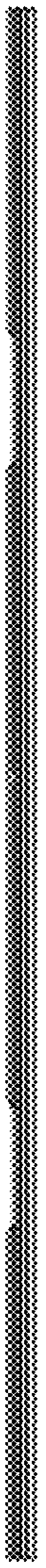

Fig. 6

Fig. 7

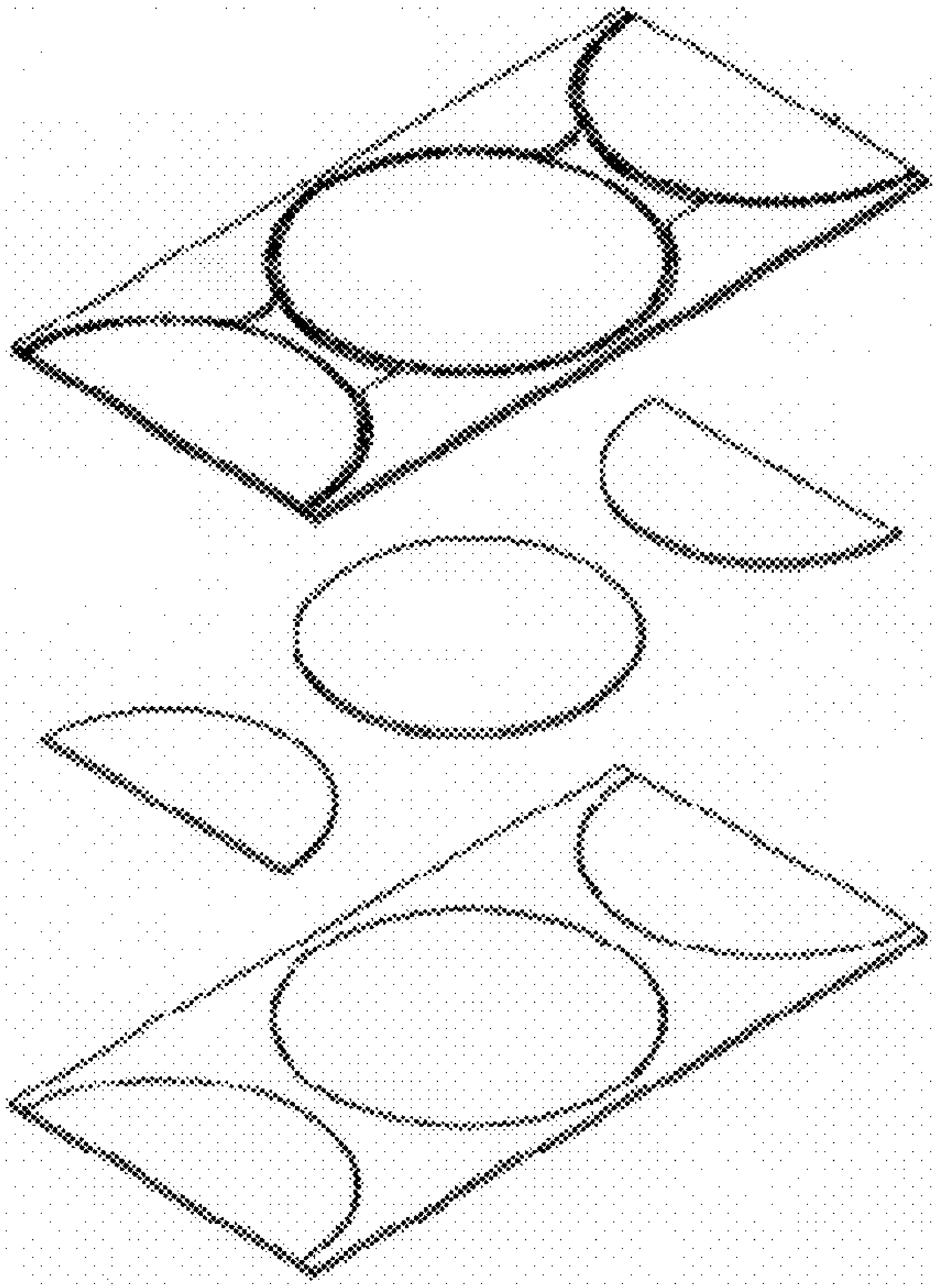

Fig. 8

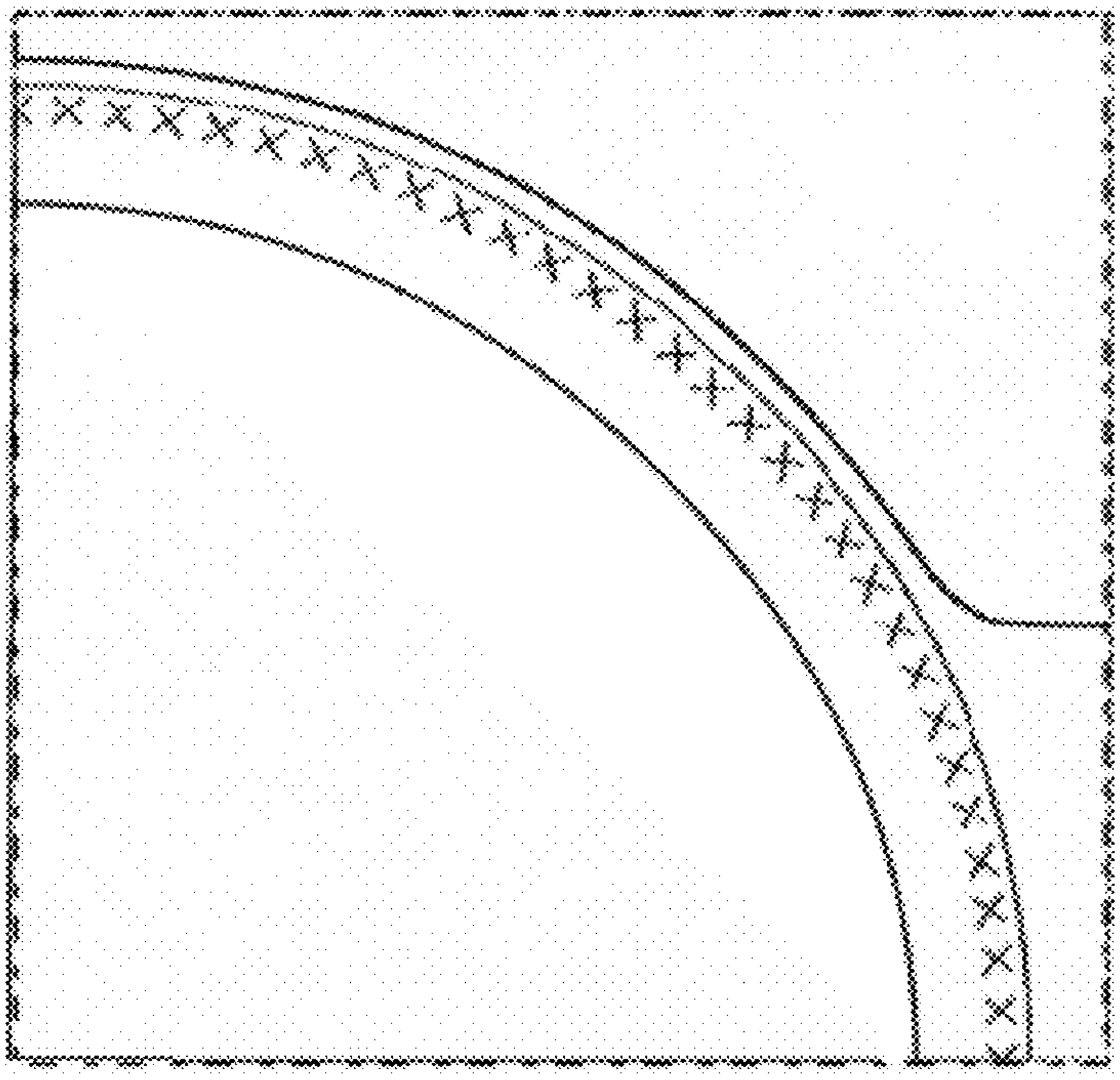

Fig. 9